

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	SAK-XC164CS-16F20F BB	**Issued**	29. August 2013
MA#	MA000964512		
Package	PG-TQFP-100-5	**Weight***	699.17 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.260	4.04	4.04	40420	40420
leadframe	non noble metal	magnesium	7439-95-4	0.282	0.04		403	
	inorganic material	silicon	7440-21-3	1.222	0.17		1747	
	non noble metal	nickel	7440-02-0	5.638	0.81		8064	
	non noble metal	copper	7440-50-8	180.785	25.86	26.88	258573	268787
wire	noble metal	gold	7440-57-5	3.501	0.50	0.50	5007	5007
encapsulation	organic material	carbon black	1333-86-4	2.322	0.33		3321	
	plastics	epoxy resin	-	62.690	8.97		89664	
	inorganic material	silicondioxide	60676-86-0	399.359	57.11	66.41	571193	664178
leadfinish	non noble metal	tin	7440-31-5	6.201	0.89	0.89	8869	8869
plating	noble metal	silver	7440-22-4	3.477	0.50	0.50	4973	4973
glue	plastics	epoxy resin	-	1.086	0.16		1553	
	noble metal	silver	7440-22-4	4.344	0.62	0.78	6213	7766
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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